

**APPARATUS AND METHOD FOR
REPAIRING ELECTRONIC PACKAGES**

ABSTRACT

A multi chip module substrate arranged with repair vias and repair lines
5 extending between repair vias of the chip sites of the module by which repairs can be
effected to overcome defects in the module circuits and a method for effecting the repairs
of defects in the circuits of this module. A defect can occur in any one of a first signal
via, a second signal via, and a circuit line extending between and intended to electrically
connect the first signal via and the second signal via. After a defective circuit is
10 identified, the signal vias of the circuit are isolated. Then, the first signal via of the
defective circuit is electrically connected to that repair via of the chip site having the first
signal via that is connected to that repair via of the chip site having the second signal via
and the second signal via of the defective circuit is electrically connected to that repair via
of the chip site having the second signal via that is connected to that repair via of the chip
15 site having the first signal via.